

30/561299

WAP2005010710 15 DEC 2005

Express Mail<sup>®</sup> mailing label number: EV 327132198 USDate of Deposit: December 15, 2005Case No. 9905/34  
Client No. BIF023273/US**UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

JOLY et al.

Serial No.: Not Yet Assigned

Filing Date: Herewith

For: INTEGRATED CIRCUIT ON  
HIGH-PERFORMANCE CHIP

Examiner:

Not Yet Assigned

Group Art Unit:

Not Yet Assigned

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

Dear Sir:

In accordance with the duty of disclosure under 37 C.F.R. §1.56 and  
§§1.97-1.98, and more particularly in accordance with 37 C.F.R. §1.97(b),  
Applicants hereby cite the following references:

**U.S. AND FOREIGN REFERENCES**

No.	Date of Issue/Publication	Patentee/Applicant/Country
US 2003/0001221 A1	01/02/2003	Fischer et al.
US 2002/0185469 A1	12/12/2002	Podlesnik et al.
US 2002/0000646 A1	01/03/2002	Gooch et al.
6,407,929 B1	06/18/2002	Hale et al.
6,310,387 B1	10/30/2001	Seefeldt et al.
6,306,720 B1	10/23/2001	Ding
5,539,241	07/23/1996	Abidi et al.
WO 03/021667 A2	03/13/2003	PCT
EP 1 096 259 A1	05/02/2001	EPO
DE 101 53 319 A1	05/15/2003	Germany

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /D.Z./

**OTHER ART**

Ayguavives et al., "Physical Properties of (Ba,Sr)TiO <sub>3</sub> Thin Films used for Integrated Capacitors in Microwave Applications", IEEE 2001.
Donohue et al., "Pulse-Extended Excimer Laser Annealing of Lead Zirconate Titanate Thin Films", proceedings of the 12th International Symposium on Integrated Ferroelectrics, Aachen, Germany, March 2000, <i>Integrated Ferroelectrics</i> , vol. 31, pages 285 to 296, 2000.
Heistand et al., "Advances in Passive Integration for C/RC Arrays & Networks with Novel Thin & Thick Film Materials", 36th Nordic IMAPS conference, Helsinki, 1999.
Hendrix et al., "Low-Temperature Process for High-Density Thin-Film Integrated Capacitors", International Conference on High-Density Interconnect and Systems Packaging, 2000.
Jenei et al., "High-Q Inductors and Capacitors on Si Substrate", IEEE 2001.
Kim et al., "A Porous-Si-based Novel Isolation Technology for Mixed-Signal Integrated Circuits", Symposium on VLSI Technology, 2000.
Liu et al., "Integrated Thin Film Capacitor Arrays", International Conference on High Density Packaging and MCMs, 1999.
Roozeboom et al., "High-Value MOS Capacitor Arrays in Ultradeep Trenches in Silicon", <i>Microelectronic Engineering</i> , vol. 53, pages 581 to 584, Elsevier Science 2000.
Tomisaka et al., "Electroplating Cu Fillings for Through-Vias for Three-Dimensional Chip Stacking" (Electronic Components and Technology Conference, 2002).

For the Examiner's convenience, Applicants are enclosing Form PTO-1449 (one sheet) and copies of cited references A8-A19. Applicants respectfully request the Examiner's consideration of the above references and entry thereof into the record of this application.

In accordance with 37 C.F.R. §1.98(a)(3), the applicants state that the document DE 101 53 319 A1 relates to a microsensor with an eutectic connection between a sensor element and a semiconductor body. A non-certified English translation of the Abstract is enclosed herewith.

Also enclosed is a copy of the International Search Report dated August 25, 2005 for corresponding PCT Application No. WO2005/000733.

By submitting this Statement, Applicants are attempting to fully comply with the duty of candor and good faith mandated by 37 C.F.R. §1.56. As such, this

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Statement is not intended to constitute an admission that any of the enclosed references, or other information referred to therein, constitutes "prior art" or is otherwise "material to patentability," as that phrase is defined in 37 C.F.R. §1.56(a).

Applicants have calculated no fee to be due in connection with the filing of this Statement. However, the Director is authorized to charge any fee deficiency associated with the filing of this Statement to a deposit account, as authorized in the Transmittal accompanying this Statement.

Respectfully submitted,

December 15, 2005

  
Jasper W. Dockrey (Reg. No. 33,868)  
Attorney for Applicants

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312/321-4200

FORM PTO-1449	SERIAL NO. Not Yet Assigned	CASE NO. 9905/34 (BIF023273/US)
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE Herewith	GROUP ART UNIT Not Yet Assigned
APPLICANTS: JOLY et al.		

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
	A1	US 2003/0001221 A1	01/02/2003	Fischer et al.		
	A2	US 2002/0185469 A1	12/12/2002	Podlesnik et al.		
	A3	US 2002/0000646 A1	01/03/2002	Gooch et al.		
	A4	6,407,929 B1	06/18/2002	Hale et al.		
	A5	6,310,387 B1	10/30/2001	Seefeldt et al.		
	A6	6,306,720 B1	10/23/2001	Ding		
	A7	5,539,241	07/23/1996	Abidi et al.		

## FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES OR NO
	A8	WO 03/021667 A2	03/13/2003	PCT		
	A9	EP 1 096 259 A1	05/02/2001	EPO		
	A10	DE 101 53 319 A1	05/15/2003	Germany		Abstract

EXAMINER  
INITIAL

## OTHER ART - NON PATENT LITERATURE DOCUMENTS

(Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.

	A11	Ayguavives et al., "Physical Properties of (Ba,Sr)TiO <sub>3</sub> Thin Films used for Integrated Capacitors in Microwave Applications", IEEE 2001.
	A12	Donohue et al., "Pulse-Extended Excimer Laser Annealing of Lead Zirconate Titanate Thin Films", proceedings of the 12th International Symposium on Integrated Ferroelectrics, Aachen, Germany, March 2000, <i>Integrated Ferroelectrics</i> , vol. 31, pages 285 to 296, 2000.
	A13	Heistand et al., "Advances in Passive Integration for C/RC Arrays & Networks with Novel Thin & Thick Film Materials", 36th Nordic IMAPS conference, Helsinki, 1999.
	A14	Hendrix et al., "Low-Temperature Process for High-Density Thin-Film Integrated Capacitors", International Conference on High-Density Interconnect and Systems Packaging, 2000.

EXAMINER

/David Zarneka/

DATE CONSIDERED

03/19/2008

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /D.Z./

FORM PTO-1449	SERIAL NO. Not Yet Assigned	CASE NO. <b>107561299</b> 9905/34 (BIF023273/US)
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EXAMINER INITIAL	OTHER ART - NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.	
A15	Jenei et al., "High-Q Inductors and Capacitors on Si Substrate", IEEE 2001.	
A16	Kim et al., "A Porous-Si-based Novel Isolation Technology for Mixed-Signal Integrated Circuits", Symposium on VLSI Technology, 2000.	
A17	Liu et al., "Integrated Thin Film Capacitor Arrays", International Conference on High Density Packaging and MCMs, 1999.	
A18	Roozeboom et al., "High-Value MOS Capacitor Arrays in Ultradeep Trenches in Silicon", <i>Microelectronic Engineering</i> , vol. 53, pages 581 to 584, Elsevier Science 2000.	
A19	Tomisaka et al., "Electroplating Cu Fillings for Through-Vias for Three-Dimensional Chip Stacking" (Electronic Components and Technology Conference, 2002).	

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Rev. Feb.-97

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